

ABSTRACT OF THE DISCLOSURE

An array module containing an array of electronic units is mounted in an installation frame. The electronic units can be mounted by rails in a hermetically sealed array housing and blind-mate connectors can connect the units to a rear plate. Blind-mate connectors also can connect the rear plate to the installation frame for external connection. A plurality of resilient mounts are fastened to the installation frame to protect the frame and storage array module from external shock. A thermal transfer mechanism transfers thermal energy between the electronic units and a region exterior to the installation frame. The electronic units can be enclosed in hermetically sealed chambers having side rails for rigidly fastened to the unit and a resilient support connecting the side rails to at least one of the covers of the hermetically sealed chamber. Thermal rails can be permanently mounted by a plurality of resilient thermal conductors to either the side rails or one of the covers, and a fastener removably mounts the thermal rails to the other of the side rails or one of the covers so that the thermal rails and resilient thermal conductors provide conduction of thermal energy between the side rails and one of the covers.

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